IGBT

This Insulated Gate Bipolar Transistor (IGBT) features a robust and cost effective Field Stop (FS) Trench construction, and provides superior performance in demanding switching applications, offering both low on state voltage and minimal switching loss. The IGBT is well suited for half bridge resonant applications. Incorporated into the device is a soft and fast co-packaged free wheeling diode with a low forward voltage.

Features

- Low Saturation Voltage using Trench with Fieldstop Technology
- Low Switching Loss Reduces System Power Dissipation
- Low Gate Charge
- Soft, Fast Free Wheeling Diode
- These are Pb-Free Devices

Typical Applications

- Inductive Heating
- Soft Switching

ABSOLUTE MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector-emitter voltage	V_{CES}	600	V
Collector current @ Tc = 25°C @ Tc = 100°C	I _C	90 45	A
Pulsed collector current, T _{pulse} limited by T _{Jmax}	I _{CM}	180	Α
Diode forward current @ Tc = 25°C @ Tc = 100°C	I _F	90 45	A
Diode pulsed current, T _{pulse} limited by T _{Jmax}	I _{FM}	180	А
Gate-emitter voltage	V_{GE}	±20	V
Power Dissipation @ Tc = 25°C @ Tc = 100°C	P _D	250 50	W
Operating junction temperature range	TJ	–55 to +150	°C
Storage temperature range	T _{stg}	-55 to +150	°C
Lead temperature for soldering, 1/8" from case for 5 seconds	T _{SLD}	260	°C

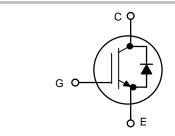
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

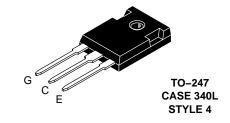


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45 A, 600 V $V_{CEsat} = 2.2 V$ $E_{off} = 0.55 \text{ mJ}$





MARKING DIAGRAM



= Assembly Location

= Year WW = Work Week = Pb-Free Package

ORDERING INFORMATION

Device	Package	Shipping
NGTB45N60SWG	TO-247 (Pb-Free)	30 Units / Rail

THERMAL CHARACTERISTICS

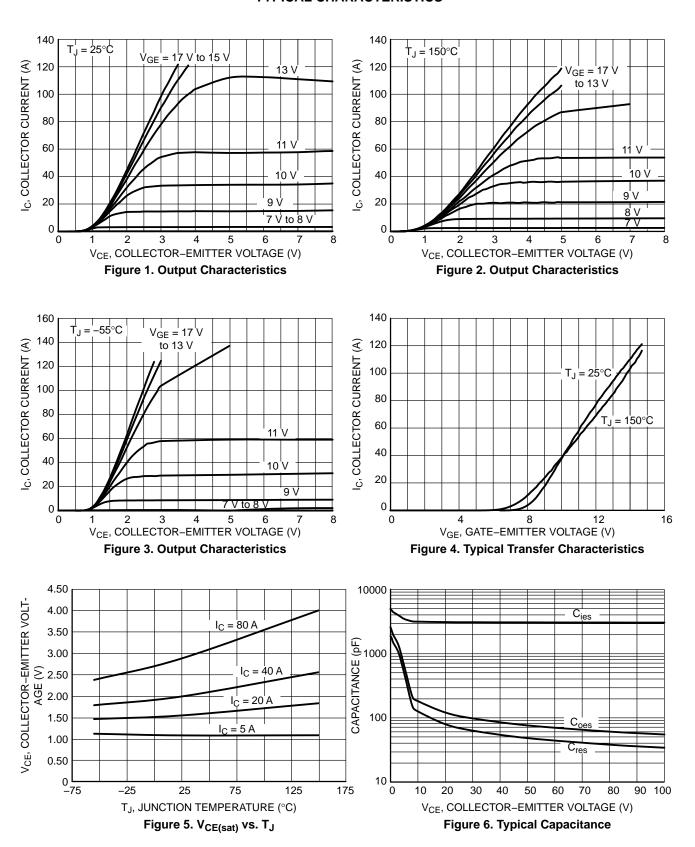
Rating	Symbol	Value	Unit
Thermal resistance junction-to-case, for IGBT	$R_{ heta JC}$	0.87	°C/W
Thermal resistance junction-to-case, for Diode	$R_{ heta JC}$	1.47	°C/W
Thermal resistance junction-to-ambient	$R_{ heta JA}$	40	°C/W

ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise specified)

Parameter	Test Conditions	Symbol	Min	Тур	Max	Unit
STATIC CHARACTERISTIC	•					
Collector–emitter breakdown voltage, gate–emitter short–circuited	$V_{GE} = 0 \text{ V, I}_{C} = 500 \mu\text{A}$	V _{(BR)CES}	600	_	-	V
Collector-emitter saturation voltage	V _{GE} = 15 V, I _C = 45 A V _{GE} = 15 V, I _C = 45 A, T _J = 150°C	V _{CEsat}	-	2.2 2.6	2.4	V
Gate-emitter threshold voltage	$V_{GE} = V_{CE}, I_{C} = 150 \mu A$	$V_{GE(th)}$	4.5	5.5	6.5	V
Collector-emitter cut-off current, gate- emitter short-circuited	V _{GE} = 0 V, V _{CE} = 600 V V _{GE} = 0 V, V _{CE} = 600 V, T _J = 150°C	I _{CES}		- -	0.2 2	mA
Gate leakage current, collector–emitter short–circuited	V _{GE} = 20 V , V _{CE} = 0 V	I _{GES}	_	-	100	nA
DYNAMIC CHARACTERISTIC	•					
Input capacitance		C _{ies}	-	3100	-	pF
Output capacitance	V _{CE} = 20 V, V _{GE} = 0 V, f = 1 MHz	C _{oes}	-	120	-	
Reverse transfer capacitance	7	C _{res}	-	80	_	
Gate charge total		Q_g		134		nC
Gate to emitter charge	$V_{CE} = 480 \text{ V}, I_{C} = 45 \text{ A}, V_{GE} = 15 \text{ V}$	Q _{ge}		27		
Gate to collector charge	7	Q _{gc}		67		
SWITCHING CHARACTERISTIC, INDUC	TIVE LOAD					
Turn-on delay time		t _{d(on)}		70		ns
Rise time	T _J = 25°C	t _r		34		1
Turn-off delay time	$V_{CC} = 400 \text{ V}, I_{C} = 45 \text{ A}$ $R_g = 10 \Omega$	t _{d(off)}		144		1
Fall time	$V_{GE} = 0 \text{ V} / 15 \text{ V}$	t _f		68		1
Turn-off switching loss	7	E _{off}		0.55		mJ
Turn-on delay time		t _{d(on)}		70		ns
Rise time	T _J = 150°C	t _r		39		1
Turn-off delay time	$V_{CC} = 400 \text{ V}, I_{C} = 45 \text{ A}$ $R_g = 10 \Omega$	t _{d(off)}		151		1
Fall time	$V_{GE} = 0 \text{ V} / 15 \text{ V}$	t _f		88		
Turn-off switching loss	7	E _{off}		0.89		mJ
DIODE CHARACTERISTIC						
Forward voltage	V _{GE} = 0 V, I _F = 20 A V _{GE} = 0 V, I _F = 20 A, T _J = 150°C	V _F		1.1 1.03	1.4	V
Reverse recovery time	T _J = 25°C	t _{rr}		376		ns
Reverse recovery charge	$I_F = 25 \text{ Å}, V_R = 200 \text{ V}$ $di_F/dt = 200 \text{ A}/\mu \text{s}$	Q _{rr}		4145		nc
Reverse recovery current	7	I _{rrm}		22		Α

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

TYPICAL CHARACTERISTICS



TYPICAL CHARACTERISTICS

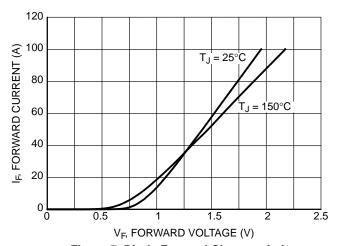


Figure 7. Diode Forward Characteristics

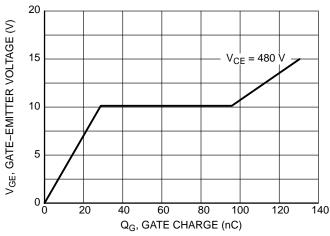


Figure 8. Typical Gate Charge

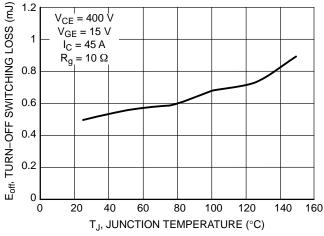


Figure 9. Switching Loss vs. Temperature

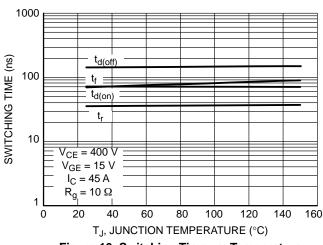


Figure 10. Switching Time vs. Temperature

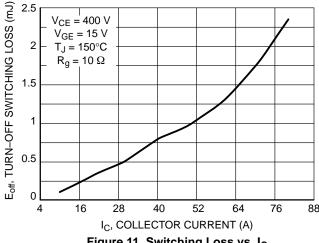


Figure 11. Switching Loss vs. I_C

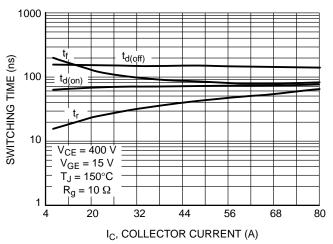


Figure 12. Switching Time vs. Current

TYPICAL CHARACTERISTICS

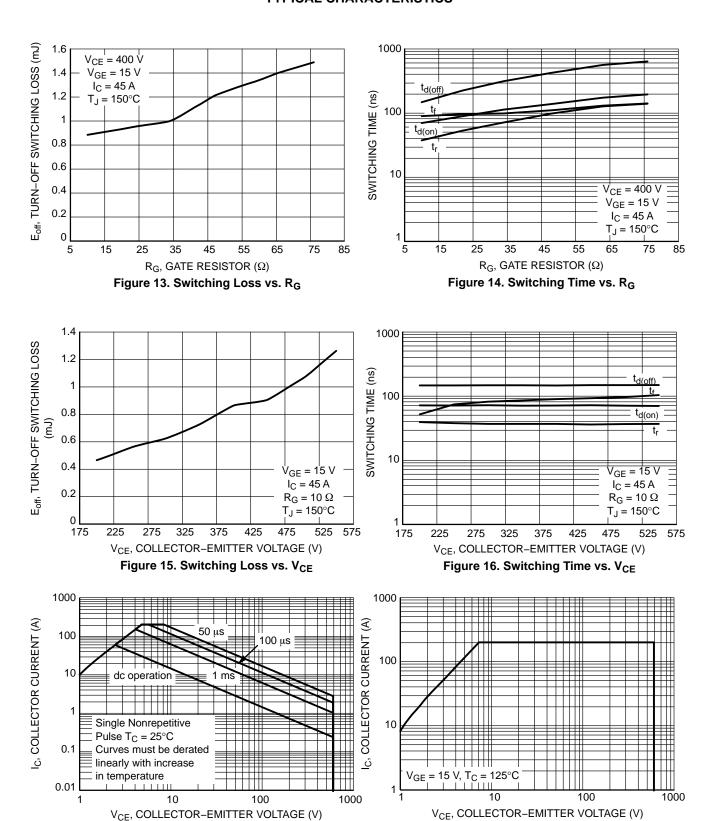


Figure 18. Reverse Bias Safe Operating Area

Figure 17. Safe Operating Area

TYPICAL CHARACTERISTICS

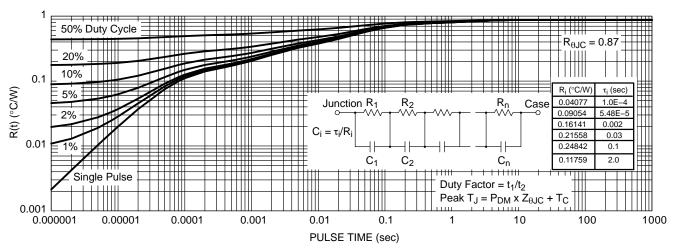


Figure 19. IGBT Transient Thermal Impedance

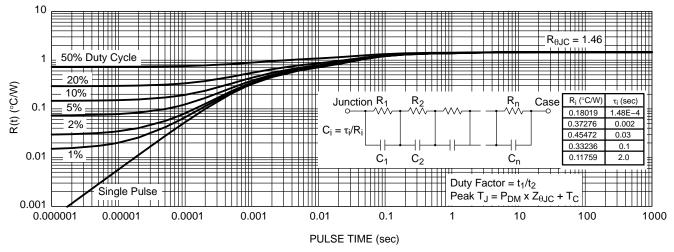


Figure 20. Diode Transient Thermal Impedance

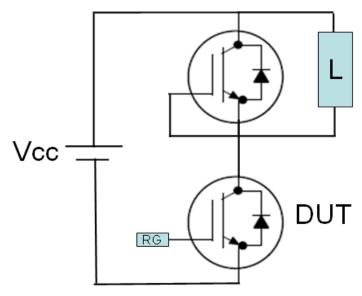


Figure 21. Test Circuit for Switching Characteristics

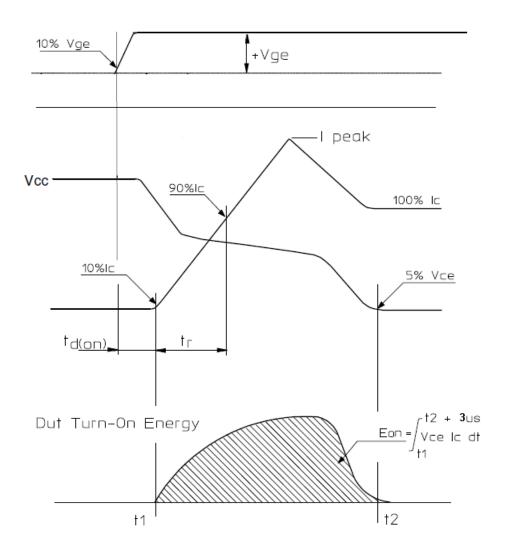


Figure 22. Definition of Turn On Waveform

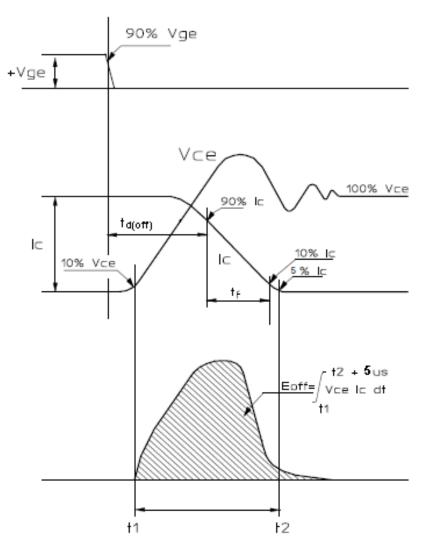
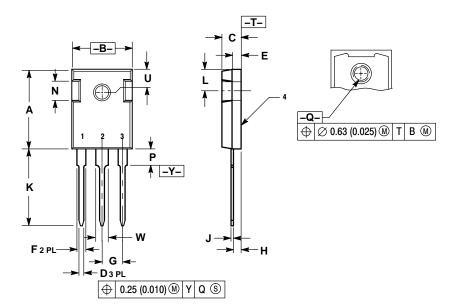


Figure 23. Definition of Turn Off Waveform

PACKAGE DIMENSIONS

TO-247 CASE 340L-02 ISSUE F



- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI
- Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.

	MILLIMETERS		INCHES		
DIM	MIN	MAX	MIN	MAX	
Α	20.32	21.08	0.800	8.30	
В	15.75	16.26	0.620	0.640	
C	4.70	5.30	0.185	0.209	
D	1.00	1.40	0.040	0.055	
Е	1.90	2.60	0.075	0.102	
F	1.65	2.13	0.065	0.084	
G	5.45 BSC		0.215 BSC		
Н	1.50	2.49	0.059	0.098	
7	0.40	0.80	0.016	0.031	
K	19.81	20.83	0.780	0.820	
L	5.40	6.20	0.212	0.244	
N	4.32	5.49	0.170	0.216	
P		4.50		0.177	
Q	3.55	3.65	0.140	0.144	
U	6.15	BSC	0.242 BSC		
W	2.87	3.12	0.113	0.123	

STYLE 4:

- PIN 1. GATE 2. COLLECTOR
 - 3. EMITTER
 - 4 COLLECTOR

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